



2020 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2020) September 2-4, 2020, Hiroshima, Japan Second Call for Papers

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The 2020 IEEE International Symposium on Radio-Frequency Integration Technology (RFIT2020) will be held at the Grand Prince Hotel Hiroshima, in Hiroshima, Japan from September 2-4, 2020. This conference is sponsored by the IEEE Microwave Theory and Techniques Society.

Travel and Safety Information

RFIT2020 is still proceeding as planned. The safety and well-being of all conference participants is our priority. We will continue to monitor official travel advisories related to the COVID-19 and update the event website to keep you informed.

Topics of interest include but not limited to

- Device Technologies: CMOS, SOI, LDMOS, SiGe, GaAs, InP, GaN, MEMS, reliability, characterization
- Modeling and CAD: active/passive device modeling, CAD, EM simulation, co-simulation
- Packaging Technology: MCM, SiP, TSV, flip chip assembly, wire bonding, anisotropic conductive film
- Passive Circuits and Antenna: on-chip antennas, integrated passive devices, ferrite, piezoelectric material
- Frequency Generation and Conversion ICs: VCOs, PLLs, synthesizers, ADPLLs, frequency dividers/multipliers, mixers
- Front-end RFICs: LNAs, VGAs, phase shifters, RF switches
- Power ICs: power amplifiers, linearization circuits, drivers
- Millimeter-wave and THz ICs: circuits operating at mm-wave (30-300 GHz) and sub-mm-wave (>300 GHz) bands
- Analog and Mixed Signal ICs: ADC, DAC, comparators, filters, AGC/VGA
- High-Speed Data Transceivers: wireless/wireline/optical transceivers, CDRs for high-speed data links
- Power Transmission ICs: RFIDs, electric coupling, electromagnetic induction, magnetic resonance, wireless power transmission ICs
- Emerging ICs: power management, digital RF circuits/architectures, RF BIST, reconfigurable and tunable ICs, vehicle electronic ICs
- Radio-Integrated Systems: IoT, automotive radars, wearable devices, security, biomedical and health care applications

Paper submission

To encourage timely reporting of the latest results and have better opportunities to expand papers for possible journal publications, prospective authors are invited to submit a 3-page manuscript (both initial submission and final manuscript, if accepted) in English and in IEEE PDF eXpress format. The manuscript should emphasize original contributions and key findings, including figures, diagrams and results from both simulations and measurements. References should be clearly cited and up-to-date. Accepted papers will be submitted to IEEE Xplore. By submitting a manuscript, the authors agree that, if accepted, at least one of the authors will make a full registration and attend the RFIT2020 to present their paper.

Manuscript submission deadline:

May 01, 2020

Notification of Acceptance:

June 08, 2020

Submission of final manuscript:

June 26, 2020

All must be made through the RFIT2020 website: <https://www.rfit2020.org>



About RFIT

RFIT is a focused yet interdisciplinary advanced forum for microwave and microelectronics. As an annual event in region 10 solely sponsored by IEEE MTT Society, it rotates among countries in region 10.

RFIT provides a forum for the integrated circuit and RF technology communities to meet and present the latest developments in integrated circuit design, technology and system integration, with emphasis on wireless communication systems and emerging applications such as IoT, biomedical and healthcare.

RFIT will continue to feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches and invited talks on technology trends and significant advances. The best papers will be selected from the contributed papers for awards. Both invited and contributed papers that are accepted by RFIT will be submitted to IEEE Xplore. Extended versions of the papers may be submitted to the IEEE Transactions on Microwave Theory and Techniques.

Hiroshima is one of the largest cities in Japan, and is the political and economic center in the Chugoku (western) region. It is also well known as the City of Water, where the six beautiful rivers flowing through it. Hiroshima area has two World Heritage sites where are Itsukushima Shrine and A-bomb Dome. With over 13 million tourists visiting Hiroshima area annual, it is one of the famous tourist attractions in Japan.



Access



[Airplane - To Hiroshima]

From Asia

Seoul	1 hr. 30 min
Dalian	2 hr.
Beijing	4 hr. 30 min
Shanghai	1 hr. 40 min
Chengdu	5 hr. 40 min
Taipei	2 hr. 25 min
Hong Kong	3 hr. 30 min
Singapore	6 hr. 45 min

[Access from within Japan]

Railroad(Shinkansen) - To Hiroshima Station

Tokyo Station	3 hr. 56 min
Shin-Yokohama Station	3 hr. 37 min
Nagoya Station	2 hr. 12 min
Kyoto Station	1 hr. 36 min
Shin-Osaka Station	1 hr. 21 min
Shin-kobe Station	1 hr. 8 min
Okayama Station	36 min
Shin-Yamaguchi Station	30 min
Kokura Station	47 min
Hakata Station	1 hr. 2 min

Airplane - To Hiroshima

Narita	1 hr. 45 min
Tokyo (Haneda)	1 hr. 30 min
Sapporo	2 hr.
Sendai	1 hr. 40 min
Okinawa	1 hr. 50 min

